

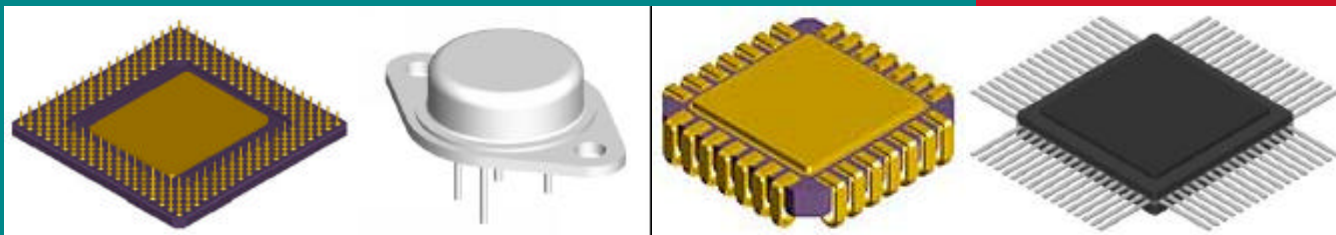
# Configuration of Hermetic Packages

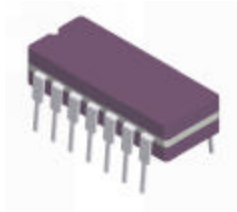
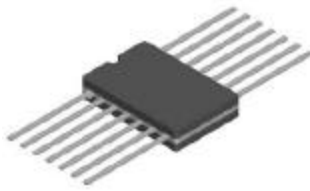
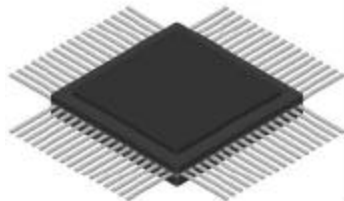
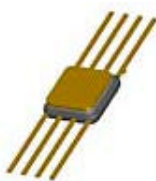
## PACKAGING

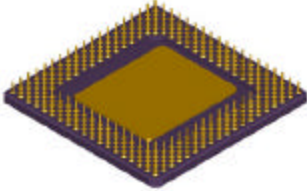
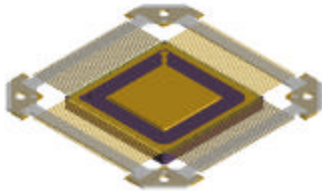
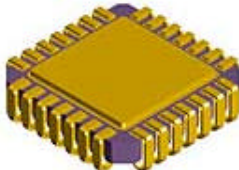
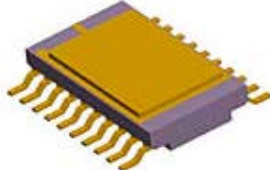
Package  
Configuration



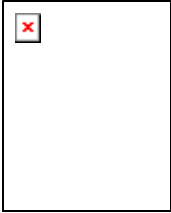

Package Codes

Package  
Characteristics



Package Configuration	Package Code	Package Characteristics
<p data-bbox="293 394 756 426"><b>Ceramic Dual-Inline-Package (CERDIP)</b></p> 	<p data-bbox="922 478 943 510"><b>J</b></p> <p data-bbox="914 541 951 573"><b>JA</b></p>	<ul data-bbox="1040 426 1430 636" style="list-style-type: none"> <li>• Through-Hole Package</li> <li>• Straight Lead Configuration</li> <li>• Solder Dip Lead Finish</li> <li>• Pressed Ceramic Package</li> <li>• Glass Seal</li> <li>• Footprint compatible with MDIP and SB</li> </ul>
<p data-bbox="347 720 703 751"><b>Ceramic Package (CERPACK)</b></p> 	<p data-bbox="922 804 943 835"><b>W</b></p> <p data-bbox="914 867 951 898"><b>WA</b></p>	<ul data-bbox="1040 741 1430 972" style="list-style-type: none"> <li>• Surface Mount or Through-Hole Package</li> <li>• Straight Lead Configuration</li> <li>• Solder Dip Lead Finish</li> <li>• Pressed Ceramic Package</li> <li>• Glass Seal</li> <li>• Footprint compatible with Flatpack</li> </ul>
<p data-bbox="310 1052 735 1083"><b>Ceramic Quad Package (CERQUAD)</b></p> 	<p data-bbox="922 1136 943 1167"><b>W</b></p> <p data-bbox="914 1199 951 1230"><b>WQ</b></p>	<ul data-bbox="1040 1041 1430 1335" style="list-style-type: none"> <li>• Surface Mount or Through-Hole Package</li> <li>• Straight Lead Configuration</li> <li>• Solder Dip or Tin Plate Lead Finish</li> <li>• Pressed Ceramic Package</li> <li>• Footprint compatible with PQFP</li> <li>• Glass Seal</li> <li>• Can be thermally and/or electrically enhanced</li> </ul>
<p data-bbox="418 1383 626 1415"><b>Ceramic Flatpack</b></p> 	<p data-bbox="922 1457 943 1488"><b>F</b></p> <p data-bbox="914 1520 951 1551"><b>FA</b></p>	<ul data-bbox="1040 1394 1430 1625" style="list-style-type: none"> <li>• Surface Mount or Through-Hole Package</li> <li>• Straight Lead Configuration</li> <li>• Gold Plate Lead Finish</li> <li>• Multilayer Ceramic Package</li> <li>• Glass Seal</li> <li>• Footprint compatible with Cerpack</li> </ul>

Package Configuration	Package Code	Package Characteristics
<p data-bbox="337 359 708 390"><b>Ceramic Pin Grid Array (CPGA)</b></p> 	<p data-bbox="922 443 943 474"><b>U</b></p> <p data-bbox="911 512 954 543"><b>UE</b></p>	<ul data-bbox="1040 407 1438 583" style="list-style-type: none"> <li>• Through-Hole Package</li> <li>• Straight Lead Configuration</li> <li>• Gold Plate Lead Finish</li> <li>• Multilayer Ceramic Package</li> <li>• Solder Seal</li> <li>• Footprint compatible with PPGA</li> </ul>
<p data-bbox="337 688 708 720"><b>Ceramic Quad Flat Pack (CQFP)</b></p> 	<p data-bbox="922 783 943 814"><b>F</b></p> <p data-bbox="911 852 954 884"><b>FA</b></p>	<ul data-bbox="1040 758 1390 905" style="list-style-type: none"> <li>• Surface Mount Package</li> <li>• Straight Lead Configuration</li> <li>• Gold Plate Lead Finish</li> <li>• Multilayer Ceramic Package</li> <li>• Solder Seal</li> </ul>
<p data-bbox="347 1041 698 1073"><b>Ceramic Quad J-Bend (CQJB)</b></p> 	<p data-bbox="911 1146 954 1178"><b>EL</b></p>	<ul data-bbox="1040 1062 1414 1262" style="list-style-type: none"> <li>• Surface Mount Package</li> <li>• J-Bend Lead Configuration</li> <li>• Gold Plate Lead Finish</li> <li>• Multilayer Ceramic Package</li> <li>• Solder Seal</li> <li>• Footprint compatible with LCC and PLCC</li> </ul>
<p data-bbox="289 1346 773 1377"><b>Ceramic Small Outline Package (CSOP)</b></p> 	<p data-bbox="911 1451 954 1482"><b>MC</b></p>	<ul data-bbox="1040 1367 1422 1566" style="list-style-type: none"> <li>• Surface Mount Package</li> <li>• Gull Wing Lead Configuration</li> <li>• Gold Plate Lead Finish</li> <li>• Multilayer Ceramic Package</li> <li>• Solder Seal</li> <li>• Footprint compatible with Wide Plastic SOP</li> </ul>

Package Configuration	Package Code	Package Characteristics
<p><b>Leadless Chip Carrier (LCC)</b></p> 	<p><b>E</b> <b>EA</b></p>	<ul style="list-style-type: none"> <li>• Surface/Socket Mount Package</li> <li>• Terminal Pads instead of Leads</li> <li>• Gold Plate or Solder Dip Lead Finish</li> <li>• Multilayer Ceramic Package</li> <li>• Solder Seal</li> <li>• Footprint compatible with CQJB and PLCC</li> </ul>
<p><b>Ceramic Sidebrazed DualIn-Line Package (SB)</b></p> 	<p><b>D</b> <b>DA</b> <b>DH</b></p>	<ul style="list-style-type: none"> <li>• Through Hole Package</li> <li>• Brazed Straight Leads to Pads on Package Side</li> <li>• Gold Plate or Solder Dip Lead Finish</li> <li>• Multilayer Ceramic Package</li> <li>• Solder Seal</li> <li>• Footprint compatible with Cerdip and MDIP</li> </ul>
<p><b>Metal Can Packages</b> <b>TO-5, TO -39, TO-46</b></p> 	<p><b>H</b> <b>HA</b></p>	<ul style="list-style-type: none"> <li>• Through-Hole Package</li> <li>• Solder Dip or Gold Plate Lead Finish</li> <li>• Kovar or Steel Base</li> <li>• Matched or Compression Glass Seal</li> </ul>
<p><b>Steel Can</b> <b>TO-3</b></p> 	<p><b>K</b> <b>KC</b> <b>KS</b> <b>KA</b></p>	<ul style="list-style-type: none"> <li>• Through-Hole Package</li> <li>• Solder Dip Lead Finish</li> <li>• Steel or Aluminium Base</li> <li>• Compression Glass Seal</li> </ul>